

In the Drawings

Please amend proposed Fig. 2 per the provided drawing sheet showing a hand-written correction in red ink.

In the Claims

(1). Please amend the claims as follows:

A3
3. **(Once Amended)** An apparatus for manufacturing a semiconductor device, comprising:

an upper electrode; and

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a pressure detecting means provided inside said upper electrode that supplies gas to a parallel-plate dry etching apparatus.

4. **(Once Amended)** The apparatus according to claim 3, wherein said upper electrode comprises a cooling plate having a plurality of gas supply holes for supplying the gas; a gas-introducing plate having gas holes for introducing the gas onto a semiconductor wafer; and a jig for fixing said gas-introducing plate to said cooling plate, wherein said pressure detecting means is provided between said gas-introducing plate and said cooling plate.

Sub B4
5. **(Once Amended)** An apparatus for manufacturing a semiconductor device, comprising:

an upper electrode;
a first pressure detecting means provided inside of said first electrode that
supplies gas in a parallel-plate dry etching apparatus; and
a second pressure detecting means provided within said dry etching
apparatus in which a wafer is placed.

7. **(Once Amended)** The apparatus according to claim 5, wherein said upper electrode comprises a cooling plate having a plurality of gas supply holes for supplying the gas, a gas-introducing plate having gas holes for introducing the gas onto a semiconductor wafer, a jig for fixing said gas-introducing plate to said cooling plate, wherein said first pressure detecting means is provided between said gas-introducing plate and said cooling plate, and wherein said second pressure detecting means is provided within an etching chamber in which said wafer is placed.

(2). Please add the following claims:

8. **(Newly Added)** An apparatus according to claim 4, wherein said gas holes increase in size during use of the apparatus, causing a fluctuation in a pressure which is measured by said pressure detecting means.

9. **(Newly Added)** An apparatus according to claim 7, wherein said gas holes increase in size during use of the apparatus, causing a difference between a pressure